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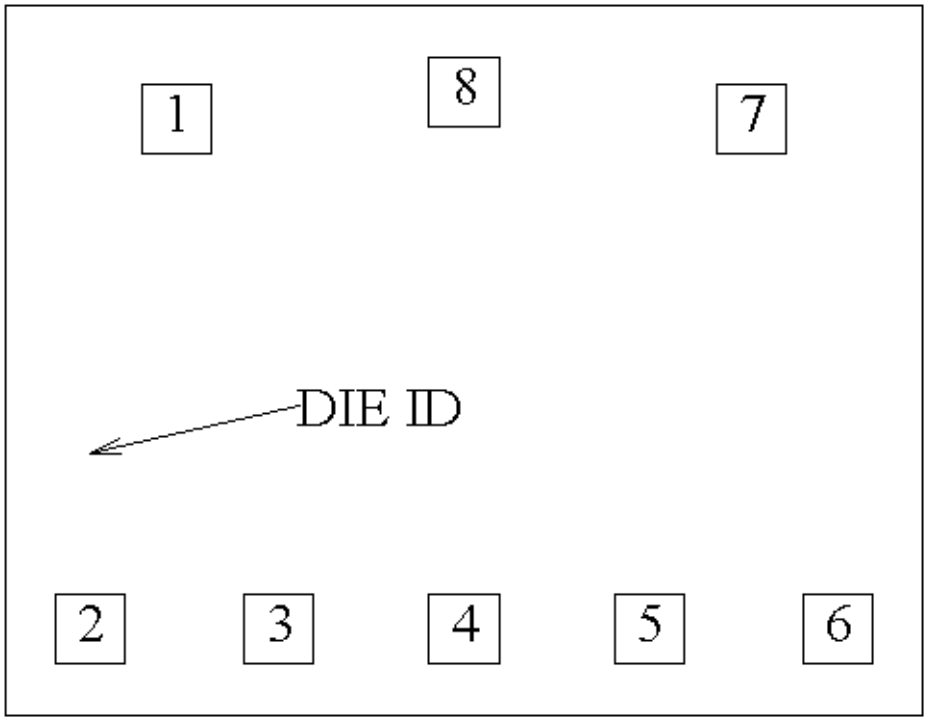
DPBU
Die Datasheet

LM258 MDC MWC
LOW POWER DUAL OPERATIONAL AMPLIFIERS

March 01,2004

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM158D	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1219µm x 940µm 48.0mils x 37.0mils	Back Side Connection	Floating or GND
Thickness	330µm Nominal		
Min Pitch	245µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT A	1	-381	320	92	x	92
INPUT A -	2	-496	-357	92	x	92
INPUT A +	3	-245	-355	92	x	92
GND	4	0	-355	92	x	92
INPUT B +	5	245	-355	92	x	92
INPUT B -	6	496	-357	92	x	92
OUTPUT B	7	381	320	92	x	92
V+	8	0	355	92	x	92

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